

MODEL : VT-9300

**INSPECTION METHOD:** Top view imaging and multi-directional lighting to give video images with 3-D edge detection, used together with CAD data and on-line standard and customized component libraries.

**BOARDS INSPECTED:** Post-solder SMT, through hole and mixed technologies. All chip components (including 0201 at high resolution), all leaded devices down to 0.4 mm fine-pitch and below. Many odd-form components including edge connectors, ois, and more.

**FAULT COVERAGE:** Component placement accuracy in X, Y and 0, missing components, component polarity, insufficient or excess solder, tombstone and billboard components, dry joints, coplanarity, shorts, lifted leads, blow holes (wave solder).

**SCAN SPEED:** Up to 26.5 cm<sup>2</sup>/sec (4.1 in<sup>2</sup>/sec).

**MAX. BOARD SIZE:** 19.7" X 15" (502mm x 380mm).

**MAX. BOARD HEIGHT:** Top: 2" (50mm); bottom: 3" (80mm).

**CONTROL SYSTEM** High-speed, latest generation Pentium-powered PC with CD-ROM and 3.5 floppy drive, 15" flat screen monitor.

**TEST PLATFORM** X, Y, Z table with high-resolution glass scale encoders.

**LIGHTING:** Multiple level and directional Xenon flash lighting array, closed loop illumination control.

**HOST COMMUNICATIONS:** Twisted pair Ethernet supporting TCP/IP or Microsoft Network.

**IMAGE PROCESSING:** Video frame-grabber card with multi-bank memory support.

**BOARD HANDLING:** Automatic board handling and width control SMEMA compatible.

**CAMERA:** Advanced 3-D imaging utilizing multiple top and angled CCD sensors and two different resolutions for high-speed and high-resolution operation.